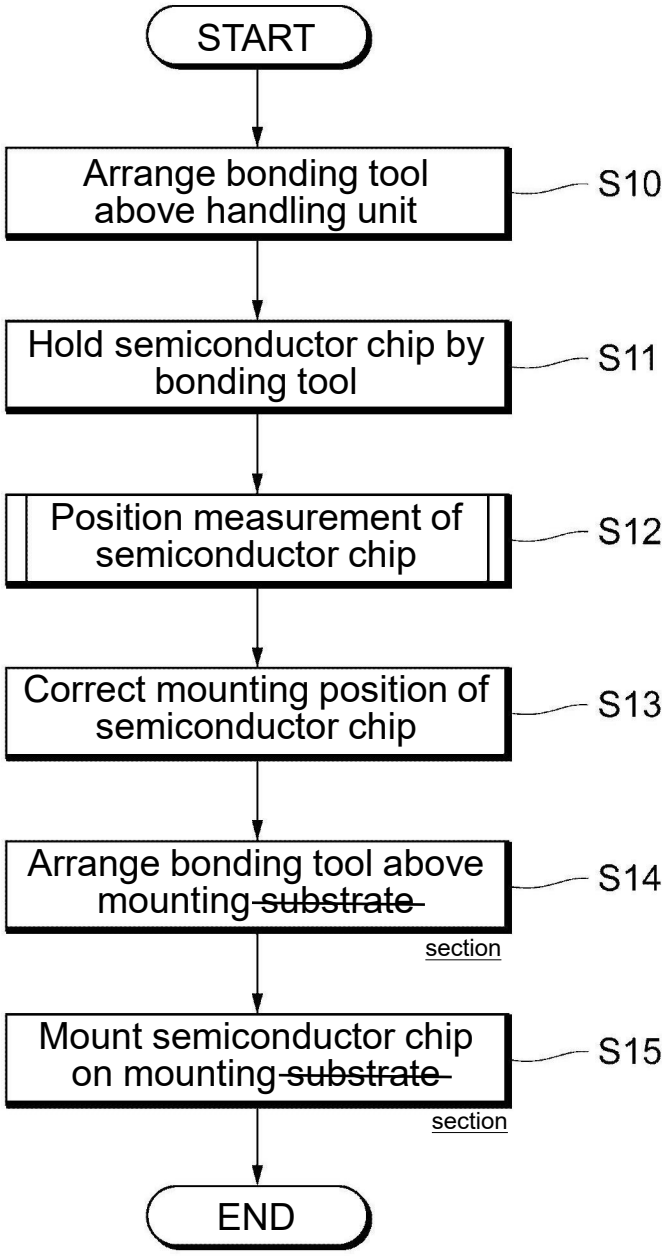
START
Arrange bonding tool above handling unit
S10
Hold semiconductor chip by bonding tool
S11
Position measurement of semiconductor chip
S12
Correct mounting position of semiconductor chip
S13
Arrange bonding tool above mounting ~~substrate~~ section
S14
Mount semiconductor chip on mounting ~~substrate~~ section
S15
END

FIG. 4